



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-16
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L151QE6	P3PG*436XXXA	A	9996	2016-02-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	70.57	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SOLDERBALL (Sn96.5Ag3.5)	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	7x7x0.6	132	No lead	
Comment	Package: A0G8 UFBGA 7X7X0.6 132L P 0.5 R 12X12 8298393			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	P3PG*436XXXA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	4.581	mg	supplier	die	Silicon (Si)	7440-21-3		3.953	mg	862912	56015
Die or Dies (choose)				supplier	metallization	Aluminium (Al)	7429-90-5		0.055	mg	12006	779
Die or Dies (choose)				supplier	metallization	Copper (Cu)	7440-50-8		0.182	mg	39729	2579
Die or Dies (choose)				supplier	metallization	Tantalum (Ta)	7440-25-7		0.021	mg	4584	298
Die or Dies (choose)				supplier	metallization	Titanium (Ti)	7440-32-6		0.027	mg	5894	383
Die or Dies (choose)				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	218	14
Die or Dies (choose)				supplier	Passivation	Silicon Nitride	12033-89-5		0.048	mg	10478	680
Die or Dies (choose)				supplier	Passivation	Silicon Oxide	7631-86-9		0.294	mg	64178	4166
SUBSTRATE (DS-7409HGB) Core	Other inorganic materials	20.090	mg	supplier	CORE	Organic resin	Trade secret		4.621	mg	230000	65477
SUBSTRATE (DS-7409HGB) Core				supplier	CORE	Other inorganic filler	Trade secret		5.223	mg	260000	74017
SUBSTRATE (DS-7409HGB) Core				supplier	CORE	Glass fiber	65997-17-3		10.246	mg	510000	145188
SUBSTRATE (DS-7409HGB) Solder Ma	Other inorganic materials	4.904	mg	supplier	SOLDERMASK	Organic resin	Trade secret		3.187	mg	650000	45167
SUBSTRATE (DS-7409HGB) Solder Ma				supplier	SOLDERMASK	Inorganic filler	Trade secret		1.716	mg	350000	24320
SUBSTRATE (DS-7409HGB) Cu	Other inorganic materials	5.657	mg	supplier	CU FOIL	Copper (Cu)	7440-50-8		5.657	mg	1000000	80154
SUBSTRATE (DS-7409HGB) Ni	Other inorganic materials	2.701	mg	supplier	NI PLATING	Nickel (Ni)	7440-02-0		2.701	mg	1000000	38267
SUBSTRATE (DS-7409HGB) Au	Other inorganic materials	0.397	mg	supplier	AU PLATING	Gold (Au)	7440-56-7		0.397	mg	1000000	5627
DIE ATTACH (ATB-130U)	Other inorganic materials	0.946	mg	supplier	GLUE	Epoxy resin	Trade secret		0.927	mg	980011	13130
DIE ATTACH (ATB-130U)				supplier	GLUE	Filler	Trade secret		0.019	mg	19989	268
BONDING WIRE (MKE 4N)	Other inorganic materials	0.960	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.960	mg	1000000	13604
SOLDERBALL (Sn96.5Ag3.5)	Other inorganic materials	4.100	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		3.960	mg	965854	56114
SOLDERBALL (Sn96.5Ag3.5)				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.140	mg	34146	1984
ENCAPSULATION (GE-100LFCS)	Other inorganic materials	26.236	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		23.043	mg	878297	326527
ENCAPSULATION (GE-100LFCS)				supplier	MOLDING COMPOUND	Epoxy resin	Trade secret		3.193	mg	121703	45246